These assemblies are ESD sensitive, ESD precautions shall be observed.
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.
These assemblies must not be washed after the HDC device is mounted.
These assemblies must not have flux contamination between the HDC device and the PCB.
Recommended to assemble and wash top side components before assembling HDC on bottom side.

Components marked 'DNP' should not be populated.
Assembly variant: 001

<table>
<thead>
<tr>
<th>PCB VIEWED FROM TOP SIDE</th>
<th>BOARD #: SENS020</th>
<th>REV: A</th>
<th>SUN REV: Not In VersionControl</th>
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<tbody>
<tr>
<td></td>
<td>TID #: TIDA-01625</td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

PLOT NAME = Top Assembly Drawing
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TEXAS INSTRUMENTS
COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: 001

PCB VIEWED FROM BOTTOM SIDE

<table>
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<tr>
<th>BOARD #</th>
<th>REV</th>
<th>SUN REV</th>
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<tbody>
<tr>
<td>SENS020</td>
<td>A</td>
<td>Not In VersionControl</td>
</tr>
</tbody>
</table>

TID #: TIDA-01625

PLOT NAME = Bottom Assembly Drawing

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